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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	4KB (4K × 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08sh4ctjr

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Chapter 4 Memory

Table 4-2. Direct-Page Register Summary (Sheet 1 of 3)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x00 00	PTAD	0	0	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
0x00 01	PTADD	0	0	PTADD5	PTADD4	PTADD3	PTADD2	PTADD1	PTADD0
0x00 02	PTBD	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0
0x00 03	PTBDD	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
0x00 04	PTCD	0	0	0	0	PTCD3	PTCD2	PTCD1	PTCD0
0x00 05	PTCDD	0	0	0	0	PTCDD3	PTCDD2	PTCDD1	PTCDD0
0x00 06 0x00 0D	Reserved	_	_	_	_	_	_	_	_
0x00 0E	ACMPSC	ACME	ACBGS	ACF	ACIE	ACO	ACOPE	ACMOD1	ACMOD0
0x00 0F	Reserved				_	_			_
0x00 10	ADSC1	0000	AIEN	ADCO			ADCH		
0x00 11	ADSC2	ADACT	ADTRG	ACFE	ACFGT	_			_
0x00 12	ADRH	0	0	0	0	0	0	ADR9	ADR8
0x00 13	ADRL	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
0x00 14	ADCVH	0	0	0	0	0	0	ADCV9	ADCV8
0x00 15	ADCVL	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
0x00 16	ADCFG	ADLPC	AC	NV	ADLSMP	MO	DE	ADI	CLK
0x00 17	APCTL1	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
0x00 18	APCTL2	0	0	0	0	ADPC11	ADPC10	ADPC9	ADPC8
0x00 19	Reserved	_	—	_				_	—
0x00 1A	IRQSC	0	IRQPDD	IRQEDG	IRQPE	IRQF	IRQACK	IRQIE	IRQMOD
0x00 1B	Reserved	_	—	_				_	—
0x00 1C	MTIMSC	TOF	TOIE	TRST	TSTP	0	0	0	0
0x00 1D	MTIMCLK	0	0	CL	KS		Р	S	
0x00 1E	MTIMCNT				CN	NT			
0x00 1F	MTIMMOD				MC	DD			
0x00 20	TPM1SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x00 21	TPM1CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 22	TPM1CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 23	TPM1MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 24	TPM1MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 25	TPM1C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x00 26	TPM1C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 27	TPM1C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 28	TPM1C1SC	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x00 29	TPM1C1VH	Bit 15	14	13	12	11	10	9	Bit 8
0x00 2A	TPM1C1VL	Bit 7	6	5	4	3	2	1	Bit 0
0x00 2B – 0x00 37	Reserved	—	_	—	—	—	—	—	—



Chapter 4 Memory

4.5.3 **Program and Erase Command Execution**

The steps for executing any of the commands are listed below. The FCDIV register must be initialized and any error flags cleared before beginning command execution. The command execution steps are:

1. Write a data value to an address in the FLASH array. The address and data information from this write is latched into the FLASH interface. This write is a required first step in any command sequence. For erase and blank check commands, the value of the data is not important. For page erase commands, the address may be any address in the 512-byte page of FLASH to be erased. For mass erase and blank check commands, the address can be any address in the FLASH memory. Whole pages of 512 bytes are the smallest block of FLASH that may be erased.

NOTE

Do not program any byte in the FLASH more than once after a successful erase operation. Reprogramming bits to a byte that is already programmed is not allowed without first erasing the page in which the byte resides or mass erasing the entire FLASH memory. Programming without first erasing may disturb data stored in the FLASH.

- 2. Write the command code for the desired command to FCMD. The five valid commands are blank check (0x05), byte program (0x20), burst program (0x25), page erase (0x40), and mass erase (0x41). The command code is latched into the command buffer.
- 3. Write a 1 to the FCBEF bit in FSTAT to clear FCBEF and launch the command (including its address and data information).

A partial command sequence can be aborted manually by writing a 0 to FCBEF any time after the write to the memory array and before writing the 1 that clears FCBEF and launches the complete command. Aborting a command in this way sets the FACCERR access error flag, which must be cleared before starting a new command.

A strictly monitored procedure must be obeyed or the command will not be accepted. This minimizes the possibility of any unintended changes to the FLASH memory contents. The command complete flag (FCCF) indicates when a command is complete. The command sequence must be completed by clearing FCBEF to launch the command. Figure 4-2 is a flowchart for executing all of the commands except for burst programming. The FCDIV register must be initialized before using any FLASH commands. This must be done only once following a reset.



4.5.5 Access Errors

An access error occurs whenever the command execution protocol is violated.

Any of the following specific actions will cause the access error flag (FACCERR) in FSTAT to be set. FACCERR must be cleared by writing a 1 to FACCERR in FSTAT before any command can be processed.

- Writing to a FLASH address before the internal FLASH clock frequency has been set by writing to the FCDIV register
- Writing to a FLASH address while FCBEF is not set (A new command cannot be started until the command buffer is empty.)
- Writing a second time to a FLASH address before launching the previous command (There is only one write to FLASH for every command.)
- Writing a second time to FCMD before launching the previous command (There is only one write to FCMD for every command.)
- Writing to any FLASH control register other than FCMD after writing to a FLASH address
- Writing any command code other than the five allowed codes (0x05, 0x20, 0x25, 0x40, or 0x41) to FCMD
- Writing any FLASH control register other than the write to FSTAT (to clear FCBEF and launch the command) after writing the command to FCMD
- The MCU enters stop mode while a program or erase command is in progress (The command is aborted.)
- Writing the byte program, burst program, or page erase command code (0x20, 0x25, or 0x40) with a background debug command while the MCU is secured (The background debug controller can only do blank check and mass erase commands when the MCU is secure.)
- Writing 0 to FCBEF to cancel a partial command

4.5.6 FLASH Block Protection

The block protection feature prevents the protected region of FLASH from program or erase changes. Block protection is controlled through the FLASH protection register (FPROT). When enabled, block protection begins at any 512 byte boundary below the last address of FLASH, 0xFFFF. (See Section 4.7.4, "FLASH Protection Register (FPROT and NVPROT)").

After exit from reset, FPROT is loaded with the contents of the NVPROT location, which is in the nonvolatile register block of the FLASH memory. FPROT cannot be changed directly from application software so a runaway program cannot alter the block protection settings. Because NVPROT is within the last 512 bytes of FLASH, if any amount of memory is protected, NVPROT is itself protected and cannot be altered (intentionally or unintentionally) by the application software. FPROT can be written through background debug commands, which allows a way to erase and reprogram a protected FLASH memory.

The block protection mechanism is illustrated in Figure 4-4. The FPS bits are used as the upper bits of the last address of unprotected memory. This address is formed by concatenating FPS7:FPS1 with logic 1 bits as shown. For example, to protect the last 1536 bytes of memory (addresses 0xFA00 through 0xFFFF), the FPS bits must be set to 1111 100, which results in the value 0xF9FF as the last address of unprotected memory. In addition to programming the FPS bits to the appropriate value, FPDIS (bit 0 of NVPROT) must

SEC01:SEC00	Description
0:0	secure
0:1	secure
1:0	unsecured
1:1	secure

Table 4-9. Security States¹

SEC01:SEC00 changes to 1:0 after successful backdoor key entry or a successful blank check of FLASH.

4.7.3 FLASH Configuration Register (FCNFG



Figure 4-7. FLASH Configuration Register (FCNFG

Table 4-10. FCNFG Register Field Descriptions

Field	Description
5 KEYACC	 Enable Writing of Access Key — This bit enables writing of the backdoor comparison key. For more detailed information about the backdoor key mechanism, refer to Section 4.6, "Security." 0 Writes to 0xFFB0–0xFFB7 are interpreted as the start of a FLASH programming or erase command. 1 Writes to NVBACKKEY (0xFFB0–0xFFB7) are interpreted as comparison key writes.

4.7.4 FLASH Protection Register (FPROT and NVPROT)

During reset, the contents of the nonvolatile location NVPROT are copied from FLASH into FPROT. This register can be read at any time. If FPDIS = 0, protection can be increased (that is, a smaller value of FPS can be written). If FPDIS = 1, writes do not change protection.



Background commands can be used to change the contents of these bits in FPROT.

Figure 4-8. FLASH Protection Register (FPROT)

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Chapter 9 Analog-to-Digital Converter (S08ADC10V1)



Figure 9-3.	Status and	Control	Register	(ADCSC1)
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Table 9-3. ADC	SC1 Register	Field Descrip	tions
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Field	Description
7 COCO	Conversion Complete Flag — The COCO flag is a read-only bit which is set each time a conversion is completed when the compare function is disabled (ACFE = 0). When the compare function is enabled (ACFE = 1) the COCO flag is set upon completion of a conversion only if the compare result is true. This bit is cleared whenever ADCSC1 is written or whenever ADCRL is read. 0 Conversion not completed 1 Conversion completed
6 AIEN	 Interrupt Enable — AIEN is used to enable conversion complete interrupts. When COCO becomes set while AIEN is high, an interrupt is asserted. 0 Conversion complete interrupt disabled 1 Conversion complete interrupt enabled
5 ADCO	 Continuous Conversion Enable — ADCO is used to enable continuous conversions. One conversion following a write to the ADCSC1 when software triggered operation is selected, or one conversion following assertion of ADHWT when hardware triggered operation is selected. Continuous conversions initiated following a write to ADCSC1 when software triggered operation is selected. Continuous conversions are initiated by an ADHWT event when hardware triggered operation is selected.
4:0 ADCH	Input Channel Select — The ADCH bits form a 5-bit field which is used to select one of the input channels. The input channels are detailed in Figure 9-4. The successive approximation converter subsystem is turned off when the channel select bits are all set to 1. This feature allows for explicit disabling of the ADC and isolation of the input channel from all sources. Terminating continuous conversions this way will prevent an additional, single conversion from being performed. It is not necessary to set the channel select bits to all 1s to place the ADC in a low-power state when continuous conversions are not enabled because the module automatically enters a low-power state when a conversion completes.

Figure 9-4. Input Channel Select

ADCH	Input Select
00000	AD0
00001	AD1
00010	AD2
00011	AD3
00100	AD4
00101	AD5
00110	AD6
00111	AD7

ADCH	Input Select
10000	AD16
10001	AD17
10010	AD18
10011	AD19
10100	AD20
10101	AD21
10110	AD22
10111	AD23



Field	Description
1 ADPC1	 ADC Pin Control 1 — ADPC1 is used to control the pin associated with channel AD1. 0 AD1 pin I/O control enabled 1 AD1 pin I/O control disabled
0 ADPC0	 ADC Pin Control 0 — ADPC0 is used to control the pin associated with channel AD0. 0 AD0 pin I/O control enabled 1 AD0 pin I/O control disabled

Table 9-9. APCTL1 Register Field Descriptions (continued)

9.3.9 Pin Control 2 Register (APCTL2)

APCTL2 is used to control channels 8–15 of the ADC module.



Figure 9-12. Pin Control 2 Register (APCTL2)

Table 9-10. APCTL2 Register Field Descriptions

Field	Description
7 ADPC15	 ADC Pin Control 15 — ADPC15 is used to control the pin associated with channel AD15. 0 AD15 pin I/O control enabled 1 AD15 pin I/O control disabled
6 ADPC14	 ADC Pin Control 14 — ADPC14 is used to control the pin associated with channel AD14. 0 AD14 pin I/O control enabled 1 AD14 pin I/O control disabled
5 ADPC13	 ADC Pin Control 13 — ADPC13 is used to control the pin associated with channel AD13. 0 AD13 pin I/O control enabled 1 AD13 pin I/O control disabled
4 ADPC12	 ADC Pin Control 12 — ADPC12 is used to control the pin associated with channel AD12. 0 AD12 pin I/O control enabled 1 AD12 pin I/O control disabled
3 ADPC11	 ADC Pin Control 11 — ADPC11 is used to control the pin associated with channel AD11. 0 AD11 pin I/O control enabled 1 AD11 pin I/O control disabled
2 ADPC10	 ADC Pin Control 10 — ADPC10 is used to control the pin associated with channel AD10. 0 AD10 pin I/O control enabled 1 AD10 pin I/O control disabled



are too fast, then the clock must be divided to the appropriate frequency. This divider is specified by the ADIV bits and can be divide-by 1, 2, 4, or 8.

9.4.2 Input Select and Pin Control

The pin control registers (APCTL3, APCTL2, and APCTL1) are used to disable the I/O port control of the pins used as analog inputs. When a pin control register bit is set, the following conditions are forced for the associated MCU pin:

- The output buffer is forced to its high impedance state.
- The input buffer is disabled. A read of the I/O port returns a zero for any pin with its input buffer disabled.
- The pullup is disabled.

9.4.3 Hardware Trigger

The ADC module has a selectable asynchronous hardware conversion trigger, ADHWT, that is enabled when the ADTRG bit is set. This source is not available on all MCUs. Consult the module introduction for information on the ADHWT source specific to this MCU.

When ADHWT source is available and hardware trigger is enabled (ADTRG=1), a conversion is initiated on the rising edge of ADHWT. If a conversion is in progress when a rising edge occurs, the rising edge is ignored. In continuous convert configuration, only the initial rising edge to launch continuous conversions is observed. The hardware trigger function operates in conjunction with any of the conversion modes and configurations.

9.4.4 Conversion Control

Conversions can be performed in either 10-bit mode or 8-bit mode as determined by the MODE bits. Conversions can be initiated by either a software or hardware trigger. In addition, the ADC module can be configured for low power operation, long sample time, continuous conversion, and automatic compare of the conversion result to a software determined compare value.

9.4.4.1 Initiating Conversions

A conversion is initiated:

- Following a write to ADCSC1 (with ADCH bits not all 1s) if software triggered operation is selected.
- Following a hardware trigger (ADHWT) event if hardware triggered operation is selected.
- Following the transfer of the result to the data registers when continuous conversion is enabled.

If continuous conversions are enabled a new conversion is automatically initiated after the completion of the current conversion. In software triggered operation, continuous conversions begin after ADCSC1 is written and continue until aborted. In hardware triggered operation, continuous conversions begin after a hardware trigger event and continue until aborted.



Chapter 9 Analog-to-Digital Converter (S08ADC10V1)

9.4.4.2 Completing Conversions

A conversion is completed when the result of the conversion is transferred into the data result registers, ADCRH and ADCRL. This is indicated by the setting of COCO. An interrupt is generated if AIEN is high at the time that COCO is set.

A blocking mechanism prevents a new result from overwriting previous data in ADCRH and ADCRL if the previous data is in the process of being read while in 10-bit MODE (the ADCRH register has been read but the ADCRL register has not). When blocking is active, the data transfer is blocked, COCO is not set, and the new result is lost. In the case of single conversions with the compare function enabled and the compare condition false, blocking has no effect and ADC operation is terminated. In all other cases of operation, when a data transfer is blocked, another conversion is initiated regardless of the state of ADCO (single or continuous conversions enabled).

If single conversions are enabled, the blocking mechanism could result in several discarded conversions and excess power consumption. To avoid this issue, the data registers must not be read after initiating a single conversion until the conversion completes.

9.4.4.3 Aborting Conversions

Any conversion in progress will be aborted when:

- A write to ADCSC1 occurs (the current conversion will be aborted and a new conversion will be initiated, if ADCH are not all 1s).
- A write to ADCSC2, ADCCFG, ADCCVH, or ADCCVL occurs. This indicates a mode of operation change has occurred and the current conversion is therefore invalid.
- The MCU is reset.
- The MCU enters stop mode with ADACK not enabled.

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered but continue to be the values transferred after the completion of the last successful conversion. In the case that the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

9.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for f_{ADCK} (see the electrical specifications).

9.4.4.5 Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit or 10-bit), and the frequency of the conversion clock (f_{ADCK}). After the module becomes active, sampling of the input begins. ADLSMP is used to select between short and long sample times. When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the digital value of the analog signal. The



Chapter 11 Inter-Integrated Circuit (S08IICV2)

11.1.4 Block Diagram

Figure 11-2 is a block diagram of the IIC.



Figure 11-2. IIC Functional Block Diagram

11.2 External Signal Description

This section describes each user-accessible pin signal.

11.2.1 SCL — Serial Clock Line

The bidirectional SCL is the serial clock line of the IIC system.

11.2.2 SDA — Serial Data Line

The bidirectional SDA is the serial data line of the IIC system.

11.3 Register Definitio

This section consists of the IIC register descriptions in address order.



Chapter 11 Inter-Integrated Circuit (S08IICV2)

11.4.3 General Call Address

General calls can be requested in 7-bit address or 10-bit address. If the GCAEN bit is set, the IIC matches the general call address as well as its own slave address. When the IIC responds to a general call, it acts as a slave-receiver and the IAAS bit is set after the address cycle. Software must read the IICD register after the first byte transfer to determine whether the address matches is its own slave address or a general call. If the value is 00, the match is a general call. If the GCAEN bit is clear, the IIC ignores any data supplied from a general call address by not issuing an acknowledgement.

11.5 Resets

The IIC is disabled after reset. The IIC cannot cause an MCU reset.

11.6 Interrupts

The IIC generates a single interrupt.

An interrupt from the IIC is generated when any of the events in Table 11-12 occur, provided the IICIE bit is set. The interrupt is driven by bit IICIF (of the IIC status register) and masked with bit IICIE (of the IIC control register). The IICIF bit must be cleared by software by writing a 1 to it in the interrupt routine. You can determine the interrupt type by reading the status register.

Interrupt Source	Status	Flag	Local Enable
Complete 1-byte transfer	TCF	IICIF	IICIE
Match of received calling address	IAAS	IICIF	IICIE
Arbitration Lost	ARBL	IICIF	IICIE

Table 11-12. Interrupt Summary

11.6.1 Byte Transfer Interrupt

The TCF (transfer complete flag) bit is set at the falling edge of the ninth clock to indicate the completion of byte transfer.

11.6.2 Address Detect Interrupt

When the calling address matches the programmed slave address (IIC address register) or when the GCAEN bit is set and a general call is received, the IAAS bit in the status register is set. The CPU is interrupted, provided the IICIE is set. The CPU must check the SRW bit and set its Tx mode accordingly.

11.6.3 Arbitration Lost Interrupt

The IIC is a true multi-master bus that allows more than one master to be connected on it. If two or more masters try to control the bus at the same time, the relative priority of the contending masters is determined by a data arbitration procedure. The IIC module asserts this interrupt when it loses the data arbitration process and the ARBL bit in the status register is set.



Chapter 11 Inter-Integrated Circuit (S08IICV2)

Chapter 16 Timer Pulse-Width Modulator (S08TPMV3)



Figure 16-1. MC9S08SH8 Block Diagram Highlighting the TPM Modules





In this mode and if (CLKSB:CLKSA not = 0:0), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer at the next change of the TPM counter (end of the prescaler counting) after the second byte is written. Instead, the TPM v2 always updates these registers when their second byte is written.

The following procedure can be used in the TPM v3 to verify if the TPMxCnVH:L registers were updated with the new value that was written to these registers (value in their write buffer).

write the new value to TPMxCnVH:L;

read TPMxCnVH and TPMxCnVL registers;

while (the read value of TPMxCnVH:L is different from the new value written to TPMxCnVH:L)

begin

. . .

read again TPMxCnVH and TPMxCnVL;

end

•••

In this point, the TPMxCnVH:L registers were updated, so the program can continue and, for example, write to TPMxC0SC without cancelling the previous write to TPMxCnVH:L registers.

— Edge-Aligned PWM (Section 16.4.2.3, "Edge-Aligned PWM Mode)

In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from \$FFFE to \$FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to \$0000.

— Center-Aligned PWM (Section 16.4.2.4, "Center-Aligned PWM Mode)

In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from \$FFFE to \$FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to (TPMxMODH:L - 1).

5. Center-Aligned PWM (Section 16.4.2.4, "Center-Aligned PWM Mode)

— TPMxCnVH:L = TPMxMODH:L [SE110-TPM case 1]

In this case, the TPM v3 produces 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

- TPMxCnVH:L = (TPMxMODH:L - 1) [SE110-TPM case 2]

In this case, the TPM v3 produces almost 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

— TPMxCnVH:L is changed from 0x0000 to a non-zero value [SE110-TPM case 3 and 5]

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Chapter 17 Development Support

When no debugger pod is connected to the 6-pin BDM interface connector, the internal pullup on BKGD chooses normal operating mode. When a debug pod is connected to BKGD it is possible to force the MCU into active background mode after reset. The specific conditions for forcing active background depend upon the HCS08 derivative (refer to the introduction to this Development Support section). It is not necessary to reset the target MCU to communicate with it through the background debug interface.

17.2.2 Communication Details

The BDC serial interface requires the external controller to generate a falling edge on the BKGD pin to indicate the start of each bit time. The external controller provides this falling edge whether data is transmitted or received.

BKGD is a pseudo-open-drain pin that can be driven either by an external controller or by the MCU. Data is transferred MSB first at 16 BDC clock cycles per bit (nominal speed). The interface times out if 512 BDC clock cycles occur between falling edges from the host. Any BDC command that was in progress when this timeout occurs is aborted without affecting the memory or operating mode of the target MCU system.

The custom serial protocol requires the debug pod to know the target BDC communication clock speed.

The clock switch (CLKSW) control bit in the BDC status and control register allows the user to select the BDC clock source. The BDC clock source can either be the bus or the alternate BDC clock source.

The BKGD pin can receive a high or low level or transmit a high or low level. The following diagrams show timing for each of these cases. Interface timing is synchronous to clocks in the target BDC, but asynchronous to the external host. The internal BDC clock signal is shown for reference in counting cycles.



17.3 On-Chip Debug System (DBG)

Because HCS08 devices do not have external address and data buses, the most important functions of an in-circuit emulator have been built onto the chip with the MCU. The debug system consists of an 8-stage FIFO that can store address or data bus information, and a flexible trigger system to decide when to capture bus information and what information to capture. The system relies on the single-wire background debug system to access debug control registers and to read results out of the eight stage FIFO.

The debug module includes control and status registers that are accessible in the user's memory map. These registers are located in the high register space to avoid using valuable direct page memory space.

Most of the debug module's functions are used during development, and user programs rarely access any of the control and status registers for the debug module. The one exception is that the debug system can provide the means to implement a form of ROM patching. This topic is discussed in greater detail in Section 17.3.6, "Hardware Breakpoints."

17.3.1 Comparators A and B

Two 16-bit comparators (A and B) can optionally be qualified with the R/W signal and an opcode tracking circuit. Separate control bits allow you to ignore R/W for each comparator. The opcode tracking circuitry optionally allows you to specify that a trigger will occur only if the opcode at the specified address is actually executed as opposed to only being read from memory into the instruction queue. The comparators are also capable of magnitude comparisons to support the inside range and outside range trigger modes. Comparators are disabled temporarily during all BDC accesses.

The A comparator is always associated with the 16-bit CPU address. The B comparator compares to the CPU address or the 8-bit CPU data bus, depending on the trigger mode selected. Because the CPU data bus is separated into a read data bus and a write data bus, the RWAEN and RWA control bits have an additional purpose, in full address plus data comparisons they are used to decide which of these buses to use in the comparator B data bus comparisons. If RWAEN = 1 (enabled) and RWA = 0 (write), the CPU's write data bus is used. Otherwise, the CPU's read data bus is used.

The currently selected trigger mode determines what the debugger logic does when a comparator detects a qualified match condition. A match can cause:

- Generation of a breakpoint to the CPU
- Storage of data bus values into the FIFO
- Starting to store change-of-flow addresses into the FIFO (begin type trace)
- Stopping the storage of change-of-flow addresses into the FIFO (end type trace)

17.3.2 Bus Capture Information and FIFO Operation

The usual way to use the FIFO is to setup the trigger mode and other control options, then arm the debugger. When the FIFO has filled or the debugger has stopped storing data into the FIFO, you would read the information out of it in the order it was stored into the FIFO. Status bits indicate the number of words of valid information that are in the FIFO as data is stored into it. If a trace run is manually halted by writing 0 to ARM before the FIFO is full (CNT = 1:0:0:0), the information is shifted by one position and



Appendix A Electrical Characteristics



Figure A-1. Typical V_{OL} vs I_{OL}, High Drive Strength



Figure A-2. Typical V_{OL} vs I_{OL} , Low Drive Strength





Figure A-8. Typical Frequency Deviation vs Temperature (ICS Trimmed to 16MHz bus@25°C, 5V, FEI)¹

^{1.} Based on the average of several hundred units from a typical characterization lot.



Characteristic	Conditions	С	Symb	Min	Typ ¹	Мах	Unit	Comment		
Supply current	ADLPC=1 ADLSMP=1 ADCO=1	Т	I _{DD} + I _{DDAD}	_	133	_	μΑ	ADC current only		
Supply current	ADLPC=1 ADLSMP=0 ADCO=1	Т	I _{DD} + I _{DDAD}		218	_	μA	ADC current only		
Supply current	ADLPC=0 ADLSMP=1 ADCO=1	Т	I _{DD} + I _{DDAD}	_	327	_	μΑ	ADC current only		
Supply current	ADLPC=0 ADLSMP=0 ADCO=1	Ρ	I _{DD} + I _{DDAD}	_	0.582	1	mA	ADC current only		
ADC asynchronous clock source	High speed (ADLPC=0)	P	f _{ADACK}	2	3.3	5	MHz	t _{ADACK} = 1/f _{ADACK}		
	Low power (ADLPC=1)			1.25	2	3.3				
Conversion time (including sample time)	Short sample (ADLSMP=0)	D	t _{ADC}	_	20		ADCK cycles	See ADC Chapter for conversion time variances		
	Long sample (ADLSMP=1)			_	40	_				
Sample time	Short sample (ADLSMP=0)	D	t _{ADS}	_	3.5		ADCK cycles			
	Long sample (ADLSMP=1)			_	23.5	_				
Total unadjusted error (Includes quantization)	10 bit mode	P	E _{TUE}		±1.5	±3.5	LSB ²			
	8 bit mode			_	±0.7	±1.5	LSB ²			
Differential Non-Linearity	10 bit mode		DNL	_	±0.5	±1.0	- LSB ²			
	8 bit mode			_	±0.3	±0.5				
	Monotonicity and No-Missing-Codes guaranteed									
Integral non-linearity	10 bit mode	т	INL	_	±0.5	±1.0	- LSB ²			
	8 bit mode			_	±0.3	±0.5				
Zero-scale error	10 bit mode	P	E _{ZS}		±1.5	±2.5	LSB ²			
	8 bit mode			_	±0.5	±0.7				
Full-scale error (V _{ADIN} = V _{DD})	10 bit mode	т	E _{FS}	0	±1.0	±1.5	- LSB ²			
	8 bit mode			0	±0.5	±0.5				
Quantization error	10 bit mode	D	EQ	_	_	±0.5	LSB ²			
	8 bit mode				—	±0.5				
Input leakage error	10 bit mode	D	E _{IL}	0	±0.2	±2.5	LSB ²	Pad leakage ² * R _{AS}		
	8 bit mode			0	±0.1	±1				

Table A-12. ADC Characteristics





VIEW D

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